

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A circuit board unit comprising:

a first substrate including, on a surface thereof, a first group of electrode terminals arranged in a matrix;

a second substrate including, on a surface thereof, a second group of electrode terminals arranged in a matrix in alignment with said first group of electrode terminals; and

an anisotropic electrical conductor sandwiched between said first and second substrates, wherein said first substrate, said anisotropic electrical conductor, and said second substrate are caused to make close contact with one another in a pressurized condition to electrically connect said first group of electrode terminals and said second group of electrode terminals to each other.
2. (original): The circuit board unit as set forth in claim 1, further comprising a pressurizer pressurizing said first substrate, said anisotropic electrical conductor, and said second substrate such that they make close contact with one another.
3. (original): The circuit board unit as set forth in claim 2, wherein said pressurizer includes a first plane which makes contact with said first substrate, a second plane which makes contact with said second substrate, and a third plane which keeps said first and second planes in parallel with each other.

4. (original): The circuit board unit as set forth in claim 3, wherein said pressurizer is composed of a material having a spring characteristic.

5. (currently amended): The circuit board unit as set forth in ~~any one of claims 1 to 4~~ claim 1, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate, and

a recess caused by said via-hole is absorbed into said anisotropic electrical conductor due to elasticity thereof when said first substrate, said anisotropic electrical conductor, and said second substrate are pressurized.

6. (currently amended): The circuit board unit as set forth in ~~any one of claims 1 to 4~~ claim 1, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate,

said each of electrode terminals has a planar area in which said via-hole is not formed, and

said each of electrode terminals makes contact with said anisotropic electrical conductor through said planar area.

7. (currently amended): The circuit board unit as set forth in ~~any one of claims 1 to 4~~ claim 1, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate,

an exposed surface of said each of electrode terminals defines a planar surface, and

said each of electrode terminals makes contact with said anisotropic electrical conductor through said exposed surface.

8. (currently amended): The circuit board unit as set forth in ~~any one of claims 1 to 7~~ claim 1, wherein said anisotropic electrical conductor includes either a metal wire selected from a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire as electrically conductive material, or one of metal particles, gold-plated particles, silver-plated particles and copper-plated particles.

9. (currently amended): The circuit board unit as set forth in ~~any one of claims 1 to 8~~ claim 1, wherein each of said first and second substrates is comprised of one of a multi-layered flexible circuit board, a multi-layered rigid printing circuit board, a double-sided flexible circuit board, and a double-sided rigid printing circuit board.

10. (currently amended): The circuit board unit as set forth in ~~any one of claims 1 to 9~~ claim 1, further comprising an adhesive layer formed on surfaces of said anisotropic electrical conductor.

11. (original): A method of connecting a first substrate including, on a surface thereof, a first group of electrode terminals, and a second substrate including, on a surface thereof, a second group of electrode terminals arranged in alignment with said first group of electrode terminals, to each other, comprising:

a first step of arranging an anisotropic electrical conductor between said first and second substrates; and

a second step of pressurizing said first substrate, said second substrate, and said anisotropic electrical conductor in a thickness-wise direction thereof to electrically connect said first group of electrode terminals and said second group of electrode terminals to each other.

12. (new): The circuit board unit as set forth in claim 2, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate, and

a recess caused by said via-hole is absorbed into said anisotropic electrical conductor due to elasticity thereof when said first substrate, said anisotropic electrical conductor, and said second substrate are pressurized.

13. (new): The circuit board unit as set forth in claim 2, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate,

said each of electrode terminals has a planar area in which said via-hole is not formed, and

said each of electrode terminals makes contact with said anisotropic electrical conductor through said planar area.

14. (new): The circuit board unit as set forth in claim 2, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate,

an exposed surface of said each of electrode terminals defines a planar surface, and

said each of electrode terminals makes contact with said anisotropic electrical conductor through said exposed surface.

15. (new): The circuit board unit as set forth in claim 2, wherein said anisotropic electrical conductor includes either a metal wire selected from a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire as electrically conductive material, or one of metal particles, gold-plated particles, silver-plated particles and copper-plated particles.

16. (new): The circuit board unit as set forth in claim 2, wherein each of said first and second substrates is comprised of one of a multi-layered flexible circuit board, a multi-layered rigid printing circuit board, a double-sided flexible circuit board, and a double-sided rigid printing circuit board.

17. (new): The circuit board as set forth in claim 2, further comprising an adhesive layer formed on surfaces of said anisotropic electrical conductor.